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For Immediate Release

Banpil Photonics, Inc. Awarded High-Speed Interconnects Patent

SANTA CLARA, California – June 15, 2013 - Banpil Photonics, Inc., a leading company expanding the boundaries of optics and electronics through innovations, today announced another high-speed interconnects patent, adding to its growing patent portfolio, which includes both optical and electrical interconnects, making up its power-efficient, high-speed interconnect platform technology for high performance computing and communications applications.

Banpil has already demonstrated the implementation and superior performance of its patented technology making it possible to increase signal-carrying capacity by more than 6 times over conventional solutions, while significantly reducing power consumption. Banpil interconnects consume a remarkable one-tenth of the power that conventional electrical interconnects utilize. Scaled to data center terms, this means a 50,000-square-foot data center which uses approximately 4 Megawatts of power would require less than 400 kilowatts to directly power its server farms by implementing Banpil interconnects. This is a timely achievement when energy conservation and environmental awareness is becoming a factor that companies need to pay attention to along with the benefits technologies deliver to society.

"We are extremely proud to obtain this new patent. We have already shown the significant performance enhancements that our high-speed metallic interconnects are capable of providing," said Dr. Achyut Dutta, Banpil's CEO. "The patent addition to our portfolio allows us to more readily work with other technology companies in joint R&D to develop next generation applications or to license our interconnect portfolio for their own high-speed application product development."

Banpil's innovations are major contributions toward the dual interconnect challenge of bandwidth performance and power efficiency in next-generation high-speed systems. Power efficiency is critical for system motherboards in computing, communications, and networking equipment. Banpil's interconnects can be used in servers and PC chipsets to connect on-board chips reducing power consumption by more than 80% compared to conventional solutions and eliminating the need for additional cooling. Banpil Flex can also replace optical interconnects used in board-to-board and rack-to-rack connections resulting in an even greater power reduction. Banpil has made sample-level high-speed FPC and rigid FR4-PCB products available for demonstration. The company welcomes opportunities to work with system vendors to explore new or enhanced applications. Banpil is also actively seeking licensees, strategic partnerships with both rigid PCB and FPC manufacturing, and investors.

About Banpil Photonics, Inc.
Banpil Photonics is expanding the boundaries of optics and electronics through innovations. Banpil develops and manufactures next generation multispectral image sensors for automotive & medical imaging systems, security & surveillance, and machine vision applications; high-efficiency energy harvesting devices for energy applications; and low-power, high-speed electrical interconnects for chip-to-chip, chip-to-board, board-to-board, and rack-to-rack applications in high performance computing and networking. The company has an extensive IP portfolio of these innovations available for licensing. For more information, visit www.banpil.com.

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